GP1S093HCZ

■ Features

- 1. General purpose
- 2. Low profile(Height:2.9mm)
- 3. Wide gap(Gap width: 2.0mm)
- 4. Slit width(Detector side):0.3mm

■ Applications

- 1. Cameras
- 2. CD-ROM drives
- 3. VCR

■ Absolute Maximum Ratings

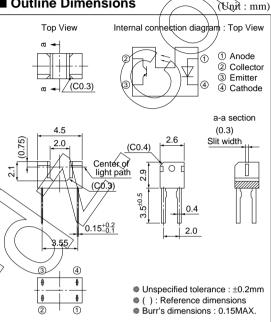
(Ta=25°C)

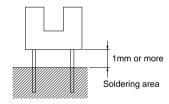
	Parameter	Symbol	Rating	Unit
Input	Forward current	I_{F}	50	mA
	Reverse voltage	VR	6	V
	Power dissipation	P	75	mW
Output	Collector-emitter voltage	Vceo	35	V
	Emitter-collector voltage	Veco	6	V
	Collector current	Ic	20	mA
	Collector power dissipation	Pc	75	mW <
Total power dissipation		Ptot	100	mW
	Operating temperature	Topr	-25 to +85	/ PC
	Storage temperature	Tstg	-40 to +100	(°C
*1 Soldering temperature		Tsol	260 ^	1.60

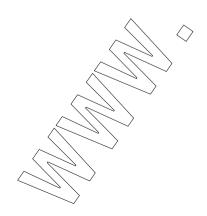




■ Outline Dimensions







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■ Electro-optical Characteristics

Parameter		Symbol	Conditions	MIN.	TYP.	MAX Unit	
Input	Forward voltage		V_F	I=20mA	-	1.2	1,A-1 V
	Reverse current		IR	V _R =3V	-		10 µA
Output	t Collector dark current		ICEO	Vce=20V	-	-	100 nA
Transfer characteristics	Collector current		Ic	V _{CE} =5V, I _F =5mA	100	- /	400 µA
	Collector-emitter saturation voltage		V _{CE(sat)}	I _F =10mA, I _C =40μA	ı	- ((0.4\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\
	Response time	Rise time	tr	$V_{\text{CE}}=5V$, $I_{\text{C}}=100\mu A$	-	50 \	150) μs
		Fall time	t f	$R_L=1~000\Omega$	_	50	150 µs

Fig.1 Forward Current vs. Ambient Temperature

Fig.3 Forward Current vs. Forward Voltage

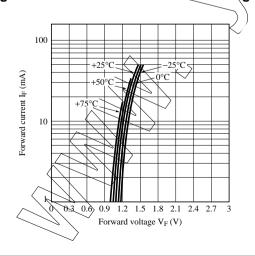


Fig.2 Power Dissipation vs. Ambient

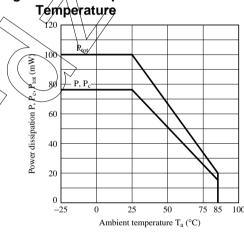
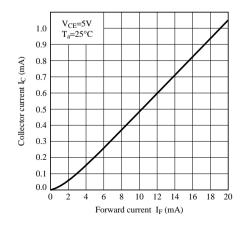


Fig.4 Collector Current vs. Forward Current



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Fig.5 Collector Current vs. Collector-emitter Voltage

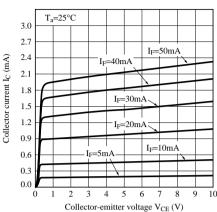


Fig.7 Collector - emitter Saturation Voltage vs. Ambient Temperature

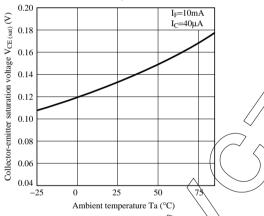


Fig.9 Response Time vs. Load Resistance

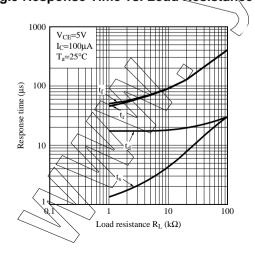


Fig.6 Relative Collector Current vs. Ambient

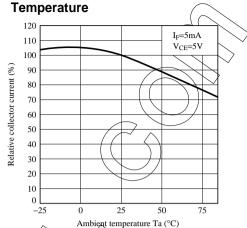


Fig.8 Collector Dark Current vs.
Ambient Temperature

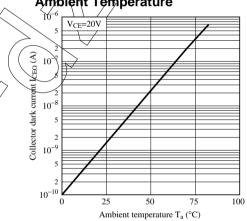
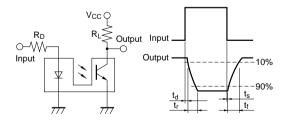


Fig.10 Test Circuit for Response Time



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Fig.12 Relative Collector Current vs. Shield Fig.11 Relative Collector Current vs. Shield Distance (2) Distance (1) 100 100 I_F=5mA I_F=5mA 90 90 V_{CE}=5V $V_{CE}=5V$ 80 80 Relative collector current (%) Relative collector current (%) 70 70 60 60 50 50 40 40 30 30 20 20 10 10 0 0.5 1.5 0.5 1.5 0 Shield distance L (mm) Shield distance L (mm)

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 - Office automation equipment
- Telecommunication equipment [terminal]
- Test and measurement equipment
- Industrial control
- Audio visual equipment
- Consumer electronics
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- Various safety devices, etc.
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